

# GSM4911P

## 40V P-Channel MOSFETs

### Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

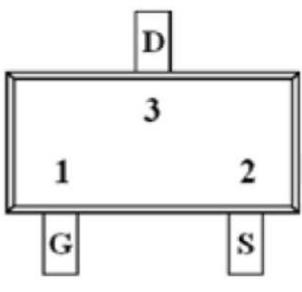
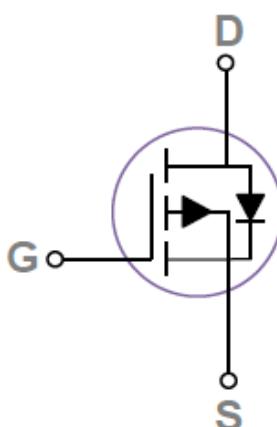
### Features

- -40V, -2.9A,  $R_{DS(ON)}=68m\Omega @ V_{GS}=-10V$
- Fast switching
- Suit for -4.5V Gate Drive Applications
- Green Device Available

### Applications

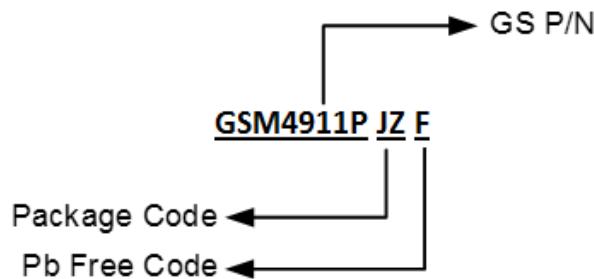
- POL Applications
- Load Switch
- LED Application

### Packages & Pin Assignments

GSM4911PJZF (SOT-23)	
	Top Views
	
Pin	Description
1	Gate
2	Source
3	Drain

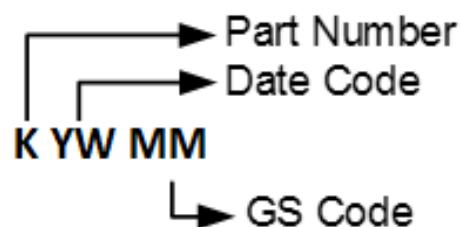
GSM4911P

## Ordering Information



Part Number	Package	Quantity
GSM4911PJZF	SOT-23	3000pcs

## Marking Information



Part Number	Package	Part Marking
GSM4911PJZF	SOT-23	KYWMM

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Typical	Unit
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$	-2.9 -2.32
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-11.6	A
$P_D$	Power Dissipation ( $T_A=25^\circ\text{C}$ )	1	W
	Power Dissipation (Derate above $25^\circ\text{C}$ )	8	$\text{mW}/^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	125	$^\circ\text{C}/\text{W}$

GSM4911P

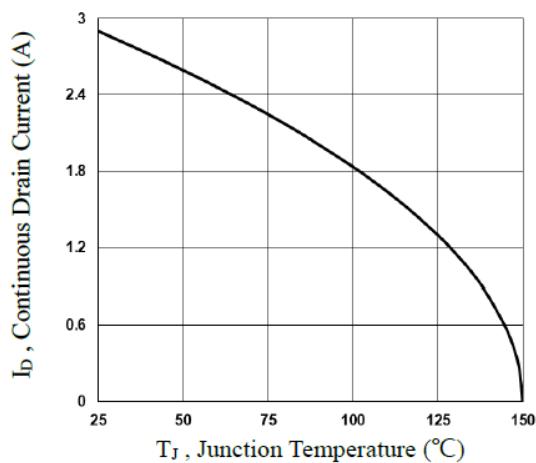
## Electrical Characteristics ( $T_J=25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-40			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.0	-1.65	-2.5	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$		$\pm 100$	nA	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-40\text{V}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$		-1		uA
		$V_{DS}=-32\text{V}, V_{GS}=0\text{V}, T_J=125^\circ\text{C}$		-10		
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current		-2.9		A
$I_{SM}$	Pulsed Source Current			-5.8		
$R_{DS(\text{on})}$	Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-2\text{A}$	55	68		mΩ
		$V_{GS}=-4.5\text{V}, I_D=-1\text{A}$	75	100		
$g_{FS}$	Forward Transconductance	$V_{DS}=-10\text{V}, I_D=-1\text{A}$	3			S
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}, I_S=-1\text{A}, T_J=25^\circ\text{C}$		-1		V
<b>Dynamic</b>						
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=-32\text{V}, V_{GS}=-10\text{V}, I_D=-2\text{A}$	6.4	13		
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		0.5	2		nC
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		2.7	6		
$C_{iss}$	Input Capacitance	$V_{DS}=-25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	600	1200		
$C_{oss}$	Output Capacitance		60	120		pF
$C_{rss}$	Reverse Transfer Capacitance		43	80		
$t_{d(on)}$	Turn-On Time <sup>2,3</sup>	$V_{DD}=-20\text{V}, I_D=-1\text{A}, V_{GS}=-10\text{V}, R_G=6\Omega$	12	24		
$t_r$	Rise Time <sup>2,3</sup>		9	20		
$t_{d(off)}$	Turn-Off Time <sup>2,3</sup>		45	90		ns
$t_f$	Fall Time <sup>2,3</sup>		5	10		

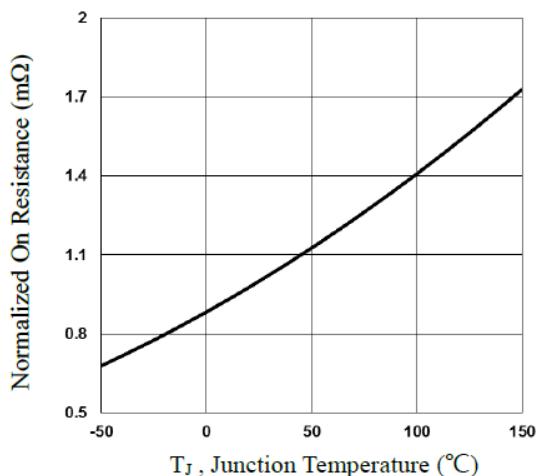
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

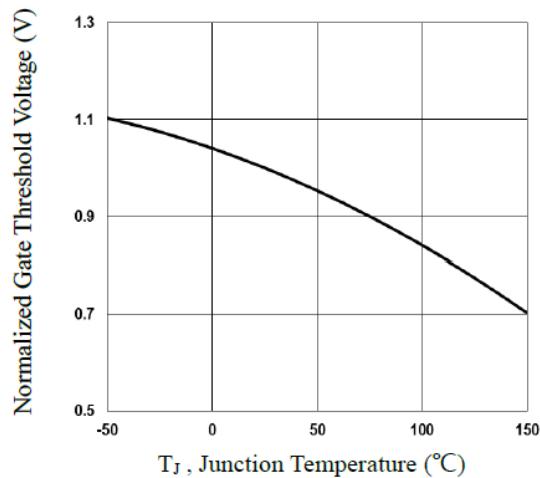
## Typical Performance Characteristics



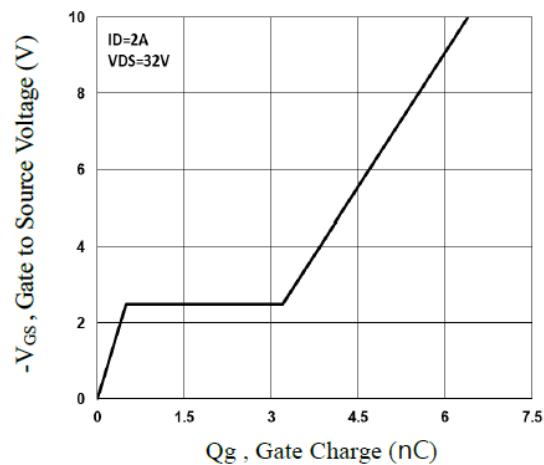
**Fig.1 Continuous Drain Current vs. T<sub>J</sub>**



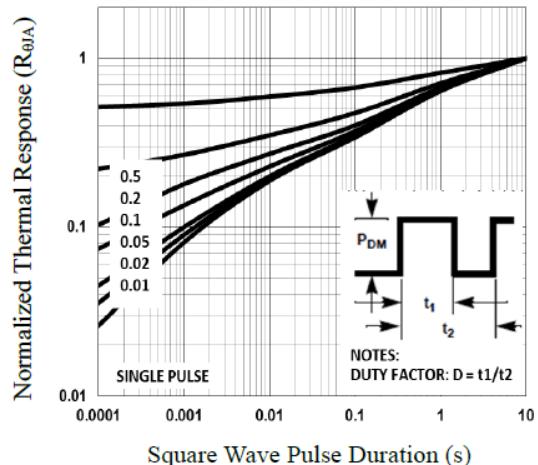
**Fig.2 Normalized RDS(on) vs. T<sub>J</sub>**



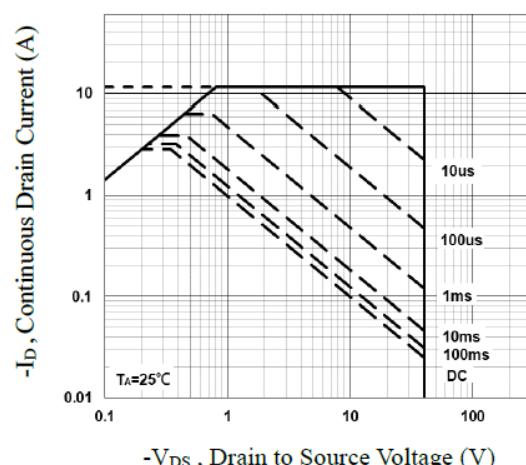
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>J</sub>**



**Fig.4 Gate Charge Waveform**



**Fig.5 Normalized Transient Impedance**



**Fig.6 Maximum Safe Operation Area**

## Typical Performance Characteristics (Continue)

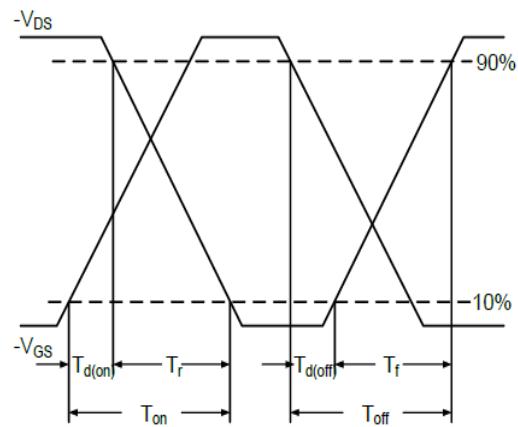


Fig.7 Switching Time Waveform

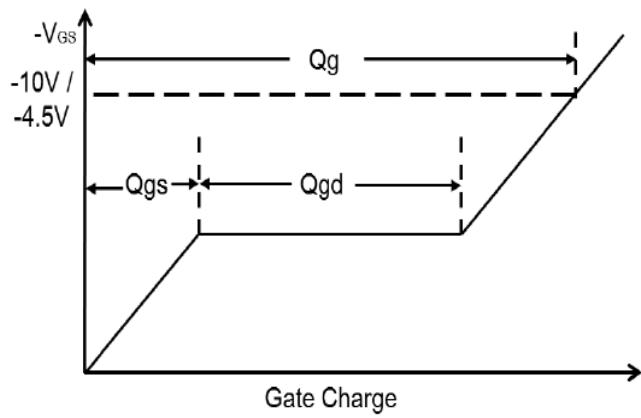
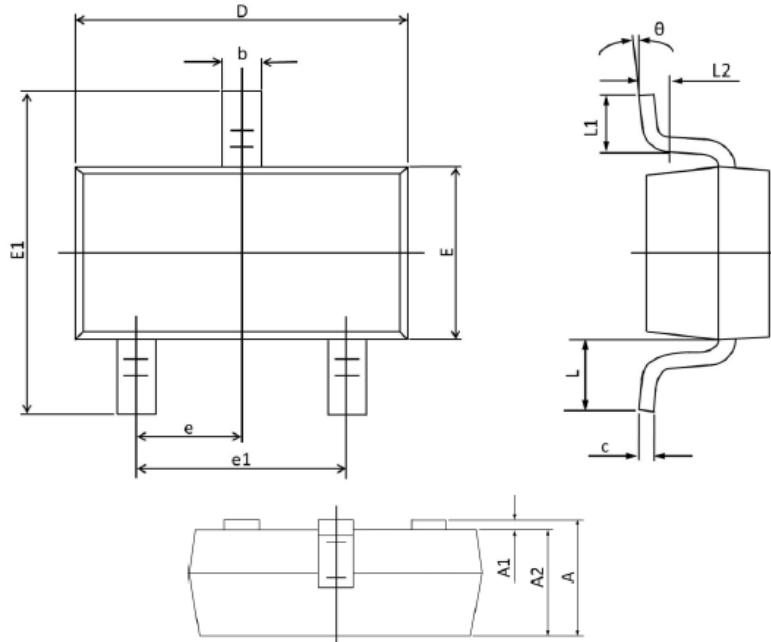


Fig.8 Gate Charge Waveform

## Package Dimension

### SOT-23



### Dimensions

Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
L2	0.250TYP		0.010TYP	
θ	0°	8°	0°	8°

GSM4911P

## NOTICE

Information furnished is believed to be accurate and reliable. However Globaltech Semiconductor assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties, which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Globaltech Semiconductor. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information without express written approval of Globaltech Semiconductor.

## CONTACT US

### GS Headquarter

	4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihu District Taipei City 114, Taiwan (R.O.C)
	886-2-2657-9980
	886-2-2657-3630
	<a href="mailto:sales_twn@gs-power.com">sales_twn@gs-power.com</a>

### RD Division

	824 Bolton Drive Milpitas. CA. 95035
	1-408-457-0587